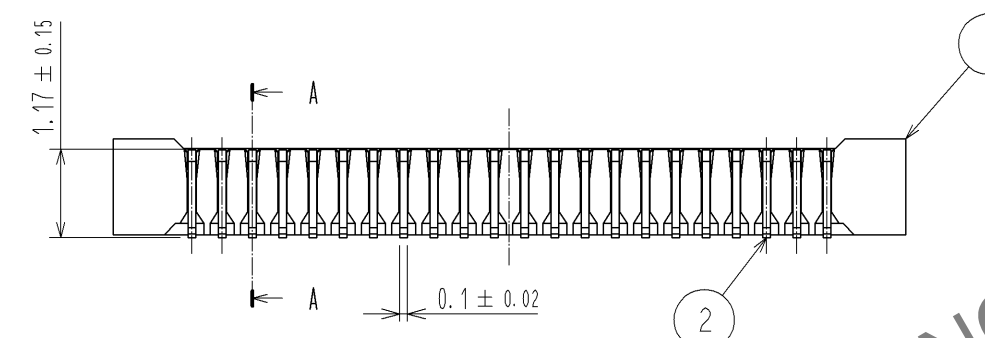
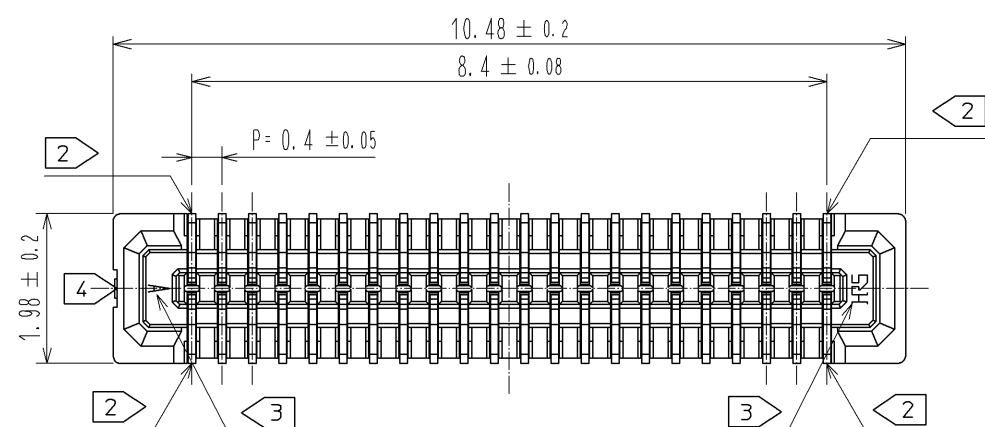
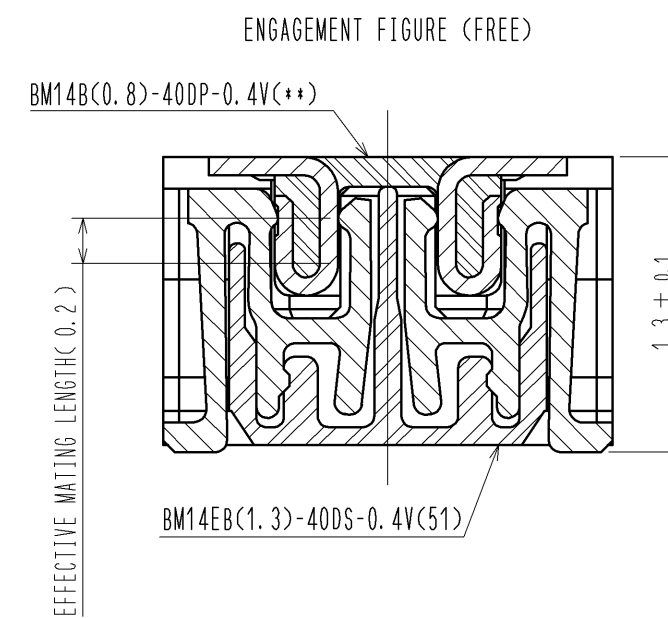
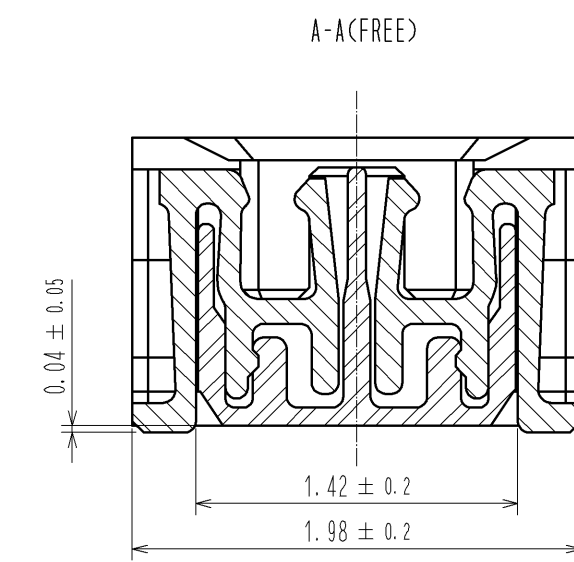




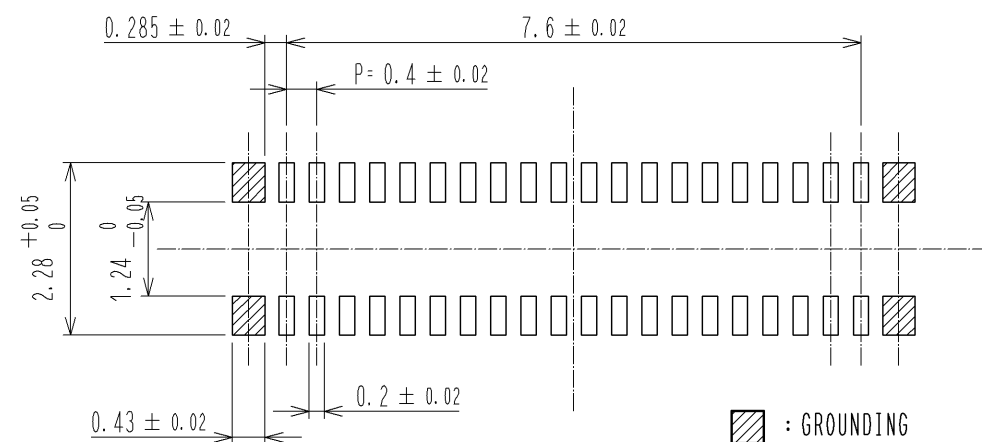
- NOTE) 1 . ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
2 . EACH CONTACTS AT 4 CORNERS ARE PROVIDED FOR METAL FITTINGS AND GROUNDING PURPOSE.
3 . HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.
4 . GATE POSITION IS INDICATED IN APPROX POSITION SHOWN.



2	PHOSPHOR BRONZE	CONTACT AREA : GOLD 0.05 μ m MIN.	6	PS	CLEAR (REINFORCEMENT COLLAR)
		SMT LEAD : GOLD 0.05 μ m MIN.	5	PS	BLACK (PLASTIC REEL)
		UNDERPLATING : NICKEL 1 μ m MIN.	4	POLYESTER	CLEAR (COVER TAPE)
1	LCP	UL94 V-0, BLACK	3	PS	CLEAR (EMBOSSED CARRIER TAPE)
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS

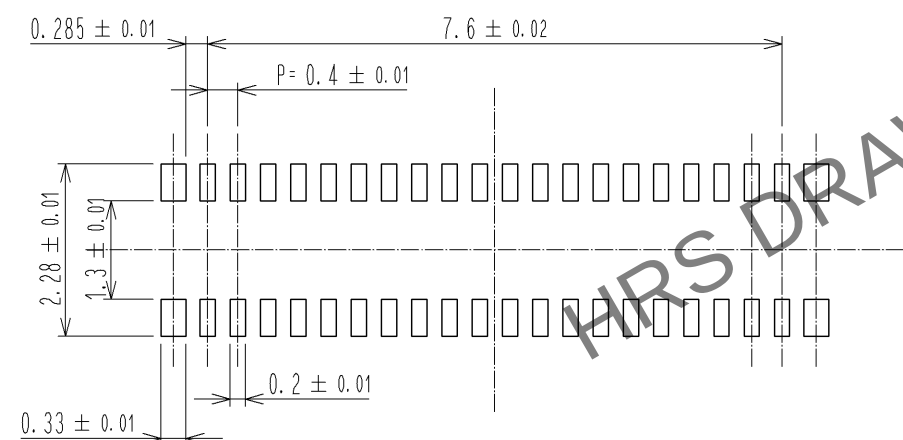
UNITS mm		SCALE		COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
		10 : 1						
 HIROSE ELECTRIC CO., LTD.	APPROVED : KH. IKEDA		14. 02. 24	DRAWING NO. EDC3-341489-01				
	CHECKED : YH. MICHIDA		14. 02. 24	PART NO. BM14EB(1.3)-40DS-0.4V(51)				
	DESIGNED : SH. HOSODA		14. 02. 21	CODE NO. CL684-8174-8-51				
	DRAWN : SH. HOSODA		14. 02. 21	 1/3				

◆ RECOMMENDED PCB LAYOUT

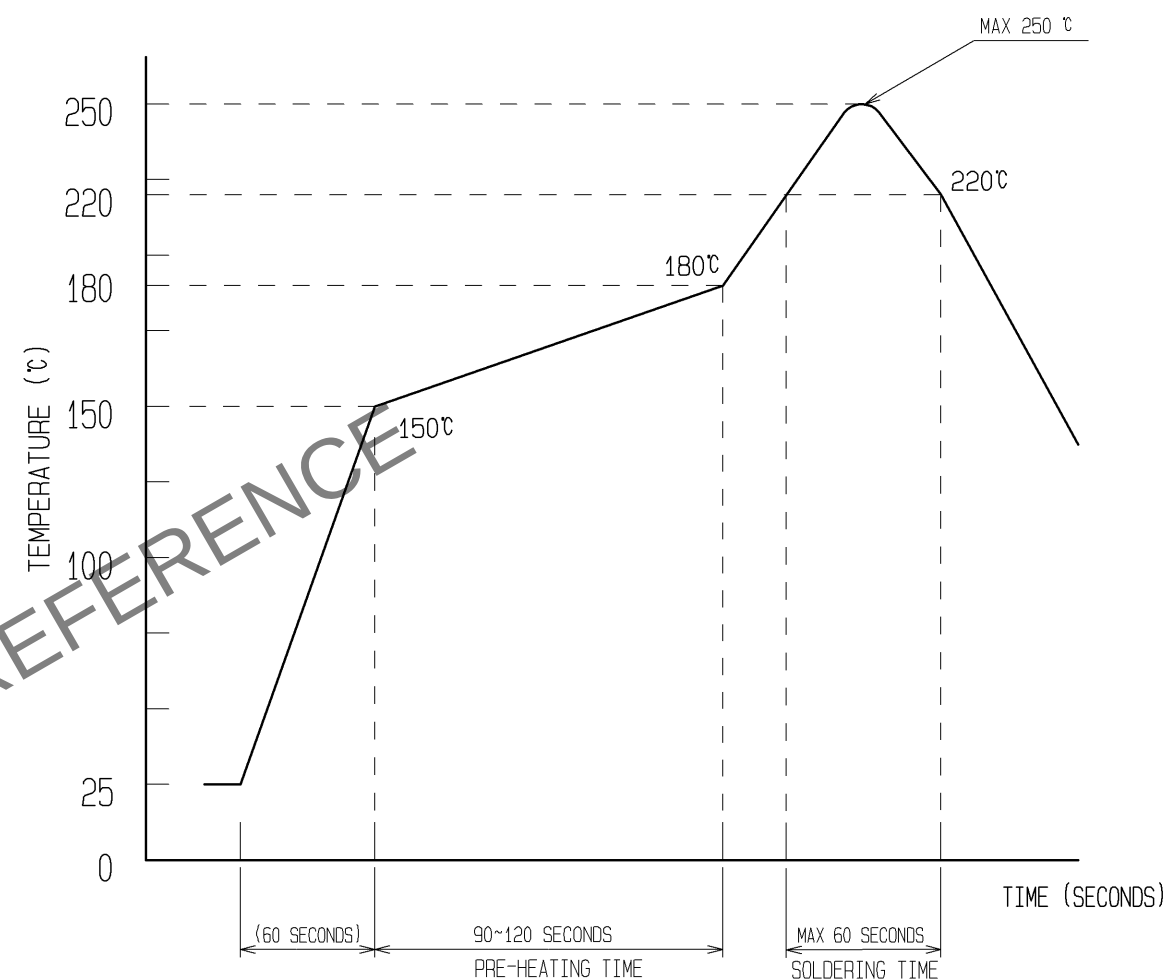


◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : $100 \mu\text{m}$



5 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD: IR REFLOW

NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.

1) REFLOW TIME

DURATION ABOVE 220°C, 60 SEC. MAX.

(PEAK TEMPERATURE: 250°C MAX)

2) PRE-HEAT TIME

PRE-HEAT TEMPERATURE(MIN): 150°C

PRE-HEAT TEMPERATURE(MAX): 180°C

PRE-HEAT TIME: 90-120 sec.

5 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

図番: EDC3-341489-01
製品名: BM14EB(1.3)-40DS-0.4V(51)
製品コード: CL684-8174-8-51

2/3

